



IC TAIWAN GRAND CHALLENGE

GLOBAL CALL
FOR PROPOSALS

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Organizer:  **國家科學及技術委員會**
National Science and Technology Council

Co-Organizers:  **semi**
國際半導體產業協會

 **TSIA** 台灣半導體產業協會
Taiwan Semiconductor Industry Association

 **TCA** 台北市電腦公會
TAIPEI COMPUTER ASSOCIATION

 **TTA** TAIWAN
TGCH ARENA

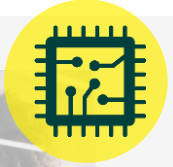
IC Taiwan Grand Challenge



Leveraging the Strengths of Silicon Island to Attract International Talents and Investment to Taiwan

- Combine **Generative AI** and **Chips** to drive industry-wide innovation
- Facilitate local professional development and attract **Global R&D Talents**
- Accelerate **Heterogeneous Integration** and **Advanced Technology**

Areas of Focus



- Startups, juristic persons, academic research institutions, and individuals that plan to collaborate with Taiwan's semiconductor chip design and manufacturing industry.
- Proposals should include core technology, situation solved, business model, market expansion plan, etc.



Domain 1

AI Core Technologies and Chips

- AI chip design
- Hardware Acceleration
- AI systems
- Generative Applications
- Large language models
- Cybersecurity

Domain 2

Smart Mobility

- Electric Vehicles
- Autonomous Vehicles
- Smart Cities
- Comms/Satellite
- Drone

Domain 3

Smart Manufacturing

- Intelligent Manufacturing
- IC Process
- Robotics

Domain 4

Smart Medtech

- Biometrics
- Smart Monitoring
- eHealth

Domain 5

Sustainability

- Sustainable Manufacturing
- Energy Saving Innovation
- New Energy

Criteria

40%

LOCAL CONNECTIVITY

1. Have a need of resources and concrete development plans in Taiwan
2. Offer Taiwan broader industry development
3. Focus on the business plans and the goals of the applicants



40%

VALUE CREATION

1. Able to drive technological innovation and create social welfare
2. Contribute to building new industrial links or enable industrial upgrading
3. Capable of raising funds or creating high economic value

20%

TECHNOLOGICAL INNOVATION

1. Possess innovation in emerging fields of application
2. Propel innovation in the manufacturing process, design, and use of new materials
3. Integrate diverse innovation and cross-domain knowledge



Benefits

1

Prize



US \$30,000

- Upon team arrival in Taiwan
- In person exhibition of innovation at 2025 TIE Expo

* details to follow

2

Mentoring

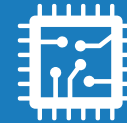


**Mentorship by
Semiconductor Industry
Experts**

- the teams will be mentored by various experts from our semiconductor industry

3

Platform



**Prototyping to Production
(EDA Tools, Wafer, etc.)**

- Each awardee, upon fulfilling the specified conditions, can receive up to a maximum of US\$3 million in product development subsidies.

4

Resources



**Multifaceted Resources and
Services to Ensure Success**

- key stakeholders of Taiwan's overall startup ecosystem will provide resources to support the challenge winners and ensure their soft landing success in Taiwan

World-class Mentors and Partners



Industry



Bor-Sung Liang
Senior Director, MediaTek



Brandon Wang
VP, Synopsys



Henry Lee
Former Technical Director,
Sunplus



Jason Jeng
Technical Director,
UMC



Jerome Hung
Vice President, M31



Konrad Young
Former Chief of RD
Department, TSMC



Kris Peng
President,
UMC Capital



Kevin Wei
Sr. Business Development,
Synopsys



Ken Li
Former President, Rafael
Microelectronics



Louis Lin
Senior Vice President,
GUC



Michel Chu
President,
ITIC



S. Z. Chang
Vice President & CTO,
PSMC



Todd Lin
COO,
EgisTec



Tsun-Jen Hou
Former RD Director,
Faraday



Tsung-Ching Wu
Co-founder and Executive of
Vice President, Atmel Corp



Weining Shen
Partner,
MediaTek Capital

Accelerator



Association



R&D Institute



University



IC Startup Accelerating Platform

Provides Critical Resources to Accelerate Semiconductor Solutions from Prototyping to Production

EDA/IP/IC Design

EDA & IP

Analog and digital processes

IC Design Service

System Integration

SI Development Factory

Module integration

Niche products market development



Wafer Manufacturing

Chip fab

Wafer shuttle

Packaging and testing supply chain

Advanced packaging testing

US\$3M in product development subsidies

- Funding in critical resources (up to US\$3M) will be in exchange of equity through SAFE (Simple Agreement for Future Equity) agreement and will be disbursed by the organizer directly to Taiwan suppliers.

Ecosystem Resources

Winners of the challenge will receive comprehensive support from the Taiwan Startup Ecosystem

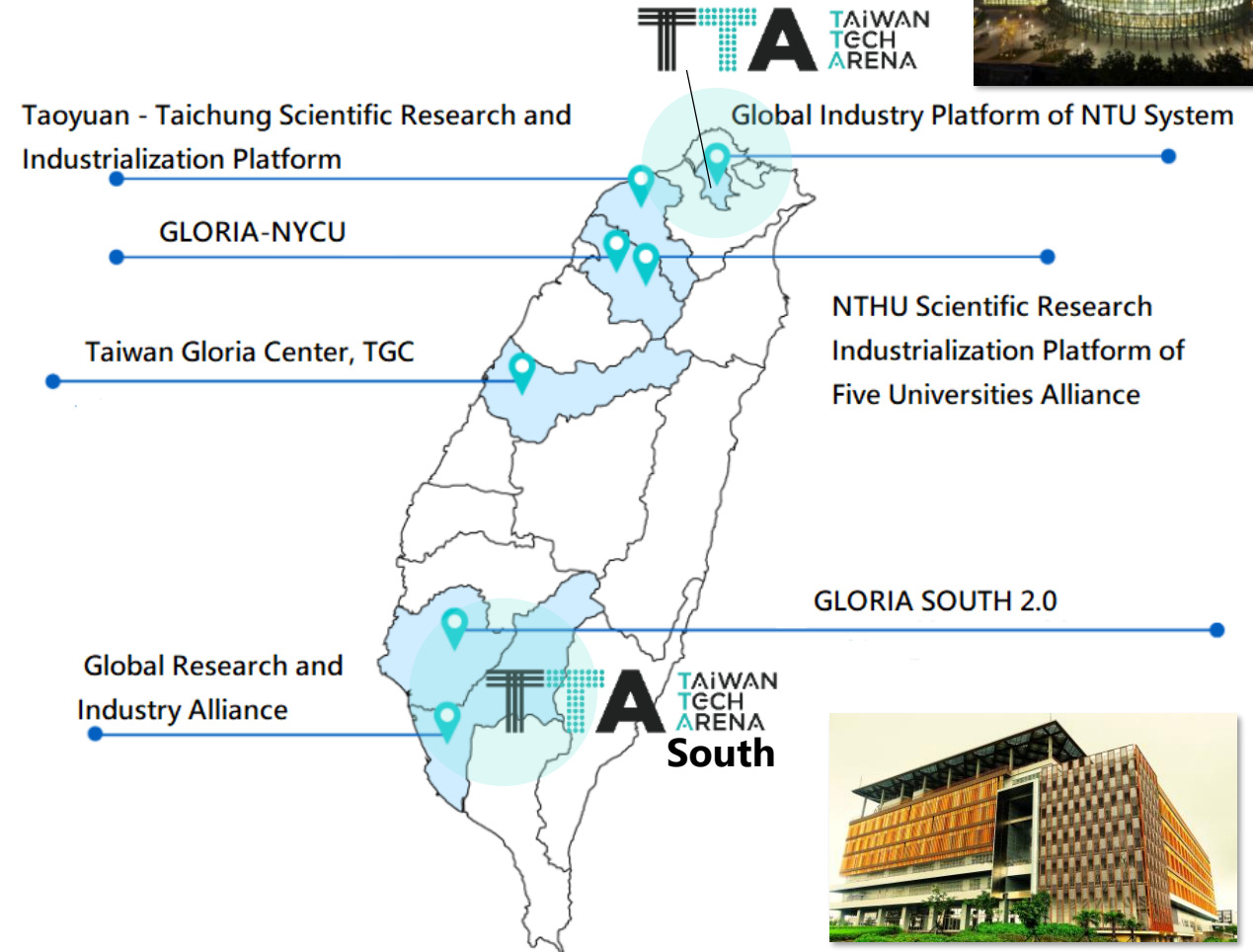
Launching
Pad for
Global
Startups

Taiwan
Employment
Gold Card

Back Office
Support

Entrepreneurial
Investor
Benefits

Academic
Resources



Top 5 Winners from 154 Teams



Origin: The United Kingdom

Quantum-Powered
Organoid-on-a-Chip

 **NSS WATER** Origin: Sweden

WET (Water Enhancement
Technology)



JMEMTEK

Origin: Singapore

PUF-Based Post-Quantum
Cryptography Hardware Security Chip



Origin: France

WiseGan & WiseWare



Origin: Singapore

TurboNext.ai LLM Platform

Competition Timeline

Mar. 26th, 2025

Online Apply **Open**

***Winning teams will attend award ceremony and exhibit at TIE expo held on Oct 16-18 in Taiwan**

TIMELINE

Jun. 30th, 2025

Online Apply **Deadline**





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Play video



Website

ictaiwanchallenge.org



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